

Title (en)
THIN FILMS OF OXIDIC MATERIALS HAVING A HIGH DIELECTRIC CONSTANT

Title (de)
DÜNNE FILME OXIDISCHER MATERIALIEN MIT HOHER DIELEKTRIZITÄTSKONSTANTE

Title (fr)
FILMS MINCES EN MATERIAUX OXYDIQUES A CONSTANCE DIELECTRIQUE ELEVEE

Publication
EP 1546437 A2 20050629 (DE)

Application
EP 03757799 A 20030908

Priority

- DE 10244285 A 20020923
- DE 10260091 A 20021219
- EP 0309945 W 20030908

Abstract (en)
[origin: WO2004028999A2] The invention relates to a method for coating a substrate, according to which a fine-particle suspension of crystalline oxide particles is applied to a substrate, the suspension medium is evaporated, and the coating is sintered on the substrate.

IPC 1-7
C23C 24/10; C04B 35/468; C04B 35/01; C04B 41/50; C23C 18/12

IPC 8 full level
B05D 1/12 (2006.01); **B05D 3/02** (2006.01); **C01G 23/00** (2006.01); **C01G 25/00** (2006.01); **C01G 35/00** (2006.01); **C04B 35/01** (2006.01); **C04B 35/468** (2006.01); **C04B 35/47** (2006.01); **C04B 35/475** (2006.01); **C04B 35/491** (2006.01); **C04B 35/645** (2006.01); **C04B 41/50** (2006.01); **C23C 18/12** (2006.01); **C23C 24/10** (2006.01); **H01L 21/316** (2006.01)

CPC (source: EP KR US)
B82Y 30/00 (2013.01 - EP US); **C01G 23/006** (2013.01 - EP KR US); **C01G 25/006** (2013.01 - EP KR US); **C01G 35/006** (2013.01 - EP KR US); **C04B 35/4682** (2013.01 - EP KR US); **C04B 35/47** (2013.01 - EP KR US); **C04B 35/475** (2013.01 - EP KR US); **C04B 35/491** (2013.01 - EP KR US); **C04B 35/6264** (2013.01 - EP KR US); **C23C 24/10** (2013.01 - KR); **H01L 21/02197** (2013.01 - KR US); **H01L 21/02282** (2013.01 - EP KR US); **H01L 21/31691** (2013.01 - US); **B82Y 30/00** (2013.01 - KR); **C01P 2004/64** (2013.01 - EP US); **C04B 2235/02** (2013.01 - EP US); **C04B 2235/3213** (2013.01 - EP US); **C04B 2235/3215** (2013.01 - EP US); **C04B 2235/3224** (2013.01 - EP US); **C04B 2235/3234** (2013.01 - EP US); **C04B 2235/3236** (2013.01 - EP US); **C04B 2235/3249** (2013.01 - EP US); **C04B 2235/3255** (2013.01 - EP US); **C04B 2235/3296** (2013.01 - EP US); **C04B 2235/3298** (2013.01 - EP US); **C04B 2235/441** (2013.01 - EP US); **C04B 2235/5454** (2013.01 - EP US); **C04B 2235/549** (2013.01 - EP US); **H01L 21/02197** (2013.01 - EP)

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)
WO 2004028999 A2 20040408; **WO 2004028999 A3 20040513**; **WO 2004028999 B1 20040617**; AU 2003273836 A1 20040419; AU 2003273836 A8 20040419; CN 100471996 C 20090325; CN 1685082 A 20051019; EP 1546437 A2 20050629; JP 2006500777 A 20060105; JP 4183681 B2 20081119; KR 20050057540 A 20050616; TW 200406263 A 20040501; TW I291903 B 20080101; US 2005220993 A1 20051006

DOCDB simple family (application)
EP 0309945 W 20030908; AU 2003273836 A 20030908; CN 03822617 A 20030908; EP 03757799 A 20030908; JP 2004538872 A 20030908; KR 20057004899 A 20050322; TW 92124896 A 20030909; US 52754805 A 20050429